

Docket No.: M4065.0503/P503
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
John W. Regnier

Allowed: December 20, 2004

Application No.: 10/050,067

Confirmation No.: 1106

Filed: January 17, 2002

Art Unit: 2825

For: A FAST ALGORITHM TO EXTRACT
FLAT INFORMATION FROM
HIERARCHICAL NETLISTS

Examiner: M. Y. Dimyan

SUBMISSION OF SUPPLEMENTAL DECLARATION

MS Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Transmitted herewith for filing in connection with the above-identified U.S. Patent Application is a Supplemental Declaration. This Supplemental Declaration identifies the citizenship of the inventor. The original Declaration filed on April 8, 2002 omitted citizenship.

Applicants believe no fees is required. Should the Applicants be incorrect, the Commissioner is authorized to charge any additional fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in this

Application No.: 10/050,067

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application by this firm) to our Deposit Account No. 04-1073, under Order No.
M4065.0503/P503.

Dated: March 10, 2005

Respectfully submitted,

By 

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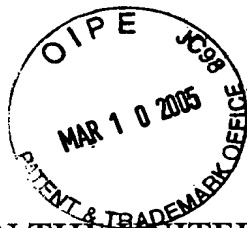
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Attorneys for Applicant



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DECLARATION FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

A FAST ALGORITHM TO EXTRACT FLAT INFORMATION FROM
HIERARCHICAL NETLISTS

the specification of which was filed on January 17, 2002 as U.S. Patent Application No. 10/050,067.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by an amendment, if any, specifically referred to in this oath or declaration.

I acknowledge the duty to disclose all information known to me which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code § 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			Priority Not Claimed
_____ (Number)	_____ (Country)	_____ (Filing Date)	<input type="checkbox"/>
_____ (Number)	_____ (Country)	_____ (Filing Date)	<input type="checkbox"/>
_____ (Number)	_____ (Country)	_____ (Filing Date)	<input type="checkbox"/>

I hereby claim the benefit under Title 35, United States Code, § 120/365 of any United States and PCT international application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code,

§ 112, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56(a) which became available between the filing date of the prior application and the national or PCT international filing date of this application:

(Application No.)	(Filing Date)	(Status) (patented, pending, abandoned)
(Application No.)	(Filing Date)	(Status) (patented, pending, abandoned)
(Application No.)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Please address all correspondence to Thomas J. D'Amico of **Dickstein Shapiro Morin & Oshinsky LLP** located at 2101 L Street NW, Washington, DC 20037-1526. Telephone calls should be made to (202) 785-9700.

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